

MEC8-DV SERIES

(0,80 mm) .0315"

VERTICAL MICRO EDGE CARD SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?MEC8-DV

Insulator Material:

Black LCP

Contact Material:

Phosphor Bronze

Plating:

Au or Sn over

50µ" (1,27 µm) Ni

Operating Temp Range:

-55°C to +125°C

Insertion Depth:

(4,22 mm) .166" to

(5,66 mm) .223"

Current Rating:

1.8 A per pin

(6 adjacent pins powered)

Voltage Rating:

185 VAC

RoHS Compliant:

Yes

Processing:

Lead-Free Solderable:

Yes

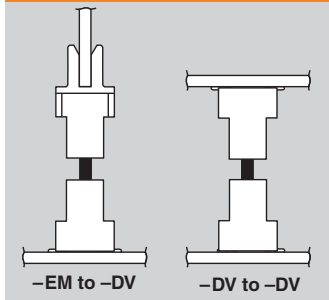
SMT Lead Coplanarity:

(0,10 mm) .004" max (10-50)

(0,15 mm) .006" max (60-70)

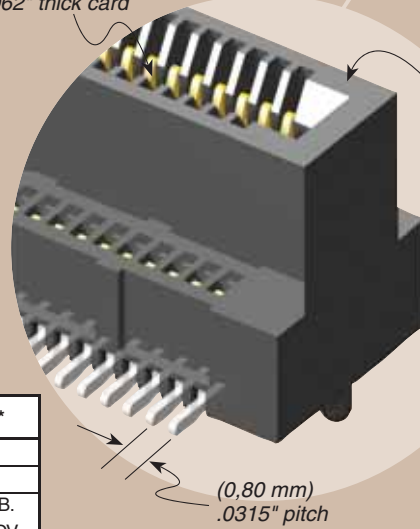
Mates with:
(1,60 mm) .062"
thick cards

APPLICATIONS



Mates with (1,60 mm)
.062" thick card

Variety of
lead counts



(0,80 mm)
.0315" pitch

MEC8-DV 8,65 mm Stack Height	Rated @ 3dB Insertion Loss*
Single-Ended Signaling	7.0 GHz / 14 Gbps
Differential Pair Signaling	7.0 GHz / 14 Gbps

*Performance data includes effects of a non-optimized PCB.
Complete test data available at www.samtec.com?MEC8-DV or contact sig@samtec.com

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



ALSO AVAILABLE (MOQ Required)

- 1 mm mating card thickness option
- Locking clip (Manual placement required)

Contact Samtec.

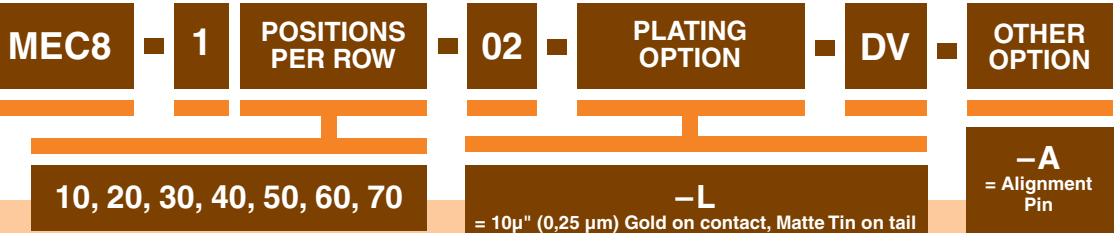
OTHER SOLUTIONS

- Right Angle
- Edge Mount

See www.samtec?MEC8-RA or www.samtec?MEC8-EM

Note: While optimized for 50Ω applications, this connector with alternative signal/ground patterns may also perform well in certain 75Ω applications. Contact Samtec for further information.

Note: Some sizes, styles and options are non-standard, non-returnable.

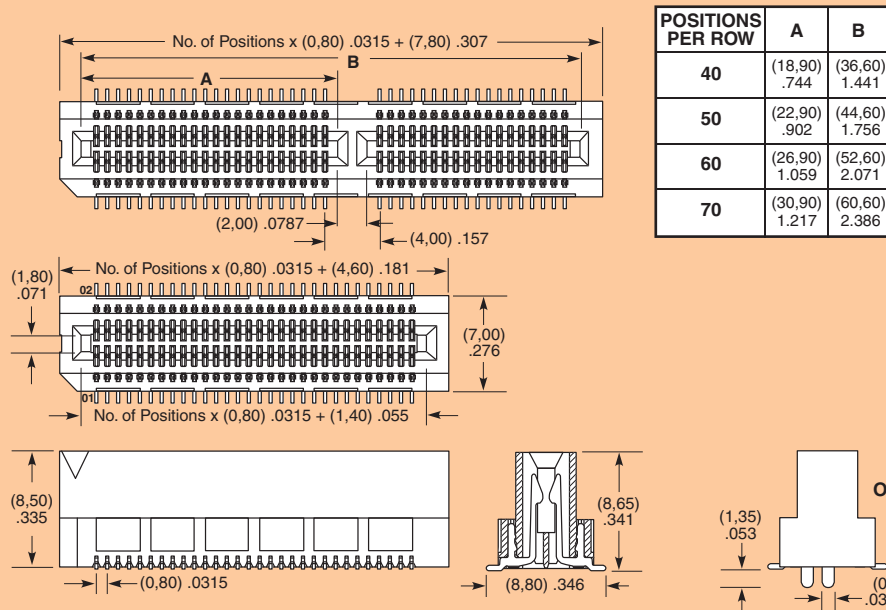


10, 20, 30, 40, 50, 60, 70

-L = 10µ" (0,25 µm) Gold on contact, Matte Tin on tail

-A = Alignment Pin

-K = (5,50 mm) .217" DIA Polyimide Pick & Place Pad



Due to technical progress, all designs, specifications and components are subject to change without notice.

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